MLCC Tin/Lead Termination "B"

X7R – General Specifications

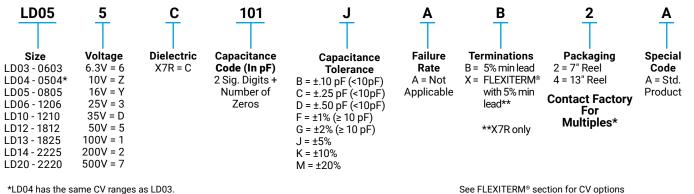




AVX Corporation will support those customers for commercial and military Multilayer Ceramic Capacitors with a termination consisting of 5% minimum lead. This termination is indicated by the use of a "B" in the 12th position of the AVX Catalog Part Number. This fulfills AVX's commitment to providing a full range of products to our customers. AVX has provided in the following pages a full range of values that we are currently offering in this special "B" termination. Please contact the factory if you require additional information on our MLCC Tin/ Lead Termination "B" products.

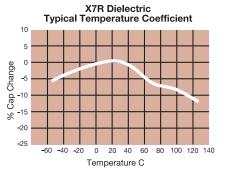
Not RoHS Compliant

PART NUMBER (SEE PAGE 4 FOR COMPLETE PART NUMBER EXPLANATION)

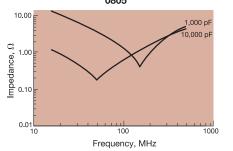


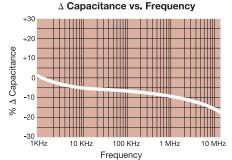
*LD04 has the same CV ranges as LD03.

NOTE: Contact factory for availability of Tolerance Options for Specific Part Numbers. Contact factory for non-specified capacitance values.

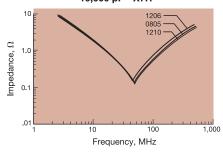


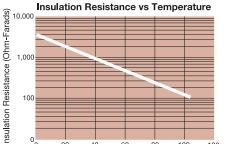






Variation of Impedance with Chip Size Impedance vs. Frequency 10,000 pF X7R





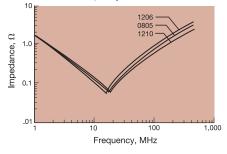
40 60 80 Temperature C

100

120

Variation of Impedance with Chip Size Impedance vs. Frequency 100,000 pF - X7R

20





The Important Information/Disclaimer is incorporated in the catalog where these specifications came from or available online at www.avx.com/disclaimer/ by reference and should be reviewed in full before placing any order.



X7R – Specifications and Test Methods

Parame	ter/Test	X7R Specification Limits	Measuring Conditions						
Operating Tem	perature Range	-55°C to +125°C	Temperature Cycle Chamber						
Сарас	itance	Within specified tolerance	-						
Dissipatio	on Factor	≤ 10% for ≥ 50V DC rating ≤ 12.5% for 25V DC rating ≤ 12.5% for 25V and 16V DC rating ≤ 12.5% for ≤ 10V DC rating	Freq.: 1.0 kHz ± 10% Voltage: 1.0Vrms ± .2V						
Insulation	Resistance	100,000MΩ or 1000MΩ - μF, whichever is less	Charge device with 120 ± 5 secs @ roo						
Dielectric	Strength	No breakdown or visual defects	Charge device with 250% of rated voltage for 1-5 seconds, w/charge and discharge current limited to 50 mA (max) Note: Charge device with 150% of rated voltage for 500V devices.						
	Appearance	No defects	Deflectio	n: 2mm					
Resistance to	Capacitance Variation	≤ ±12%	Test Time: 3						
Flexure Stresses	Dissipation Factor	Meets Initial Values (As Above)							
	Insulation Resistance	≥ Initial Value x 0.3	90	mm					
Solder	ability	≥ 95% of each terminal should be covered with fresh solder	Dip device in eutection for 5.0 ± 0.						
	Appearance	No defects, <25% leaching of either end terminal							
	Capacitance Variation	≤ ±7.5%							
Resistance to Solder Heat	Dissipation Factor	Meets Initial Values (As Above)	Dip device in eutectic s seconds. Store at room	temperature for 24 ± 2					
	Insulation Resistance	Meets Initial Values (As Above)	hours before measuring	g electrical properties.					
	Dielectric Strength	Meets Initial Values (As Above)		1					
	Appearance	No visual defects	Step 1: -55°C ± 2°	30 ± 3 minutes					
	Capacitance Variation	≤ ±7.5%	Step 2: Room Temp	≤ 3 minutes					
Thermal Shock	Dissipation Factor	Meets Initial Values (As Above)	Step 3: +125°C ± 2°	30 ± 3 minutes					
	Insulation Resistance	Meets Initial Values (As Above)	Step 4: Room Temp	≤ 3 minutes					
	Dielectric Strength	Meets Initial Values (As Above)	Repeat for 5 cycles and measure after 24 ± 2 hours at room temperature						
	Appearance	No visual defects	-						
	Capacitance Variation	≤ ±12.5%	Charge device with 1.5 rated voltage (≤ 10V) in test chamber set at 125°C ± 2°C						
Load Life	Dissipation Factor	≤ Initial Value x 2.0 (See Above)	for 1000 hou	ırs (+48, -0)					
	Insulation Resistance	≥ Initial Value x 0.3 (See Above)	Remove from test chamb temperature for 24 ± 2 h						
	Dielectric Strength	Meets Initial Values (As Above)							
	Appearance	No visual defects	-						
	Capacitance Variation	≤ ±12.5%	Store in a test chamber s 5% relative humidi	ty for 1000 hours					
Load Humidity	Dissipation Factor	≤ Initial Value x 2.0 (See Above)	(+48, -0) with rated voltage applied. Remove from chamber and stabilize at room temperature and humidity for 24 ± 2 hours before measuring.						
	Insulation Resistance	≥ Initial Value x 0.3 (See Above)							
	Dielectric Strength	Meets Initial Values (As Above)							



The Important Information/Disclaimer is incorporated in the catalog where these specifications came from or available online at www.avx.com/disclaimer/ by reference and should be reviewed in full before placing any order.

MLCC Tin/Lead Termination "B"



X7R – Capacitance Range

PREFERRED SIZES ARE SHADED

								-														Ē				
SIZE			LD02		ļ			LD03				LD05 Reflow/Wave						LD06 Reflow/Wave								
Solderin			low/V					low/V																		
Packagi	ng mm	All Paper 1.00 ± 0.10						All Paper 1.60 ± 0.15					Paper/Embossed 2.01 ± 0.20							3.20 ± 0.20						
(L) Length	(in.)		(0.040 ± 0.004) (0.063 ± 0.006)							2.01 ± 0.20 (0.079 ± 0.008)						(0.126 ± 0.008)										
W) Width	mm (in.)		50 ± 0 20 ± 0					81 ± 0 32 ± 0							25 ± 0 49 ± 0				1.60 ± 0.20							
	mm		$\frac{20 \pm 0}{25 \pm 0}$					35 ± 0							$\frac{49 \pm 0}{50 \pm 0}$				(0.063 ± 0.008) 0.50 ± 0.25							
(t) Terminal	(in.)		10 ± 0					14 ± 0							20 ± 0				(0.00 ± 0.23) (0.020 ± 0.010)							
WVDC		16	25	50	6.3	10	16	25	50	100	200	6.3	10	16	25	50	100	200	6.3	10	16	25	50	100	200	500
Сар	100																									
(pF)	150																									
(P)	220			С																						
	330			C					G	G	G		J	J	J	J	J	J								К
	470			c					G	G	G		J	J	J	J	J	J								K
	680			C C					G	G	G		J	J	J	J	J	J								K
	1000			C					G	G	G		J	J	J	J	J	J								K
	1500			c					G	G	0		J	J	J	J	J	J		J	J	J		J	J	M
	2200			C					G	G				J	J	J	J	J		J	J	-	J	J	J	M
	3300		С	C					G	G			J	J	J	J	J	J		J	J	J	J	J	J	M
	4700		c						G	G			J	J	J	J	J	J		J	J	J	J	J	J	M
	6800	С	C C						G	G			J	J	J	J	J	J		J	J		J	J	J	P
0		<u>с</u>							G	G			-	-	-		-	-		-	-	J	-	-	-	P
Cap	0.010							0		G			J	J	J	J	J	J		J	J	J	J	J	J	P
(µF)	0.015	С						G	G				J	J	J	J	J	J		J	J	J	J	J	M	
	0.022	C						G	G				J	J	J	J	J	N		J	J	J	J	J	M	
	0.033	С						G	G				J	J	J	J	N			J	J	J	J	J	M	
	0.047						G	G	G				J	J	J	J	N			J	J	J	J	J	M	
	0.068		01				G	G	G				J	J	J	J	N	ļ		J	J	J	J	J	P	
	0.10		C*			G	G	G	G				J	J	J	J	N			J	J	J	J	P	P	
	0.15				G	G							J	J	J	N	N			J	J	J	J	Q		
	0.22				G	G							J	J	N	N	N			J	J	J	J	Q		
	0.33												N	N	N	N	N			J	J	M	P	Q		
	0.47							J*					N	N	N	N	N			М	M	м	P	Q		
	0.68												N	N	N					M	M	Q	Q	Q		
	1.0					J*	J*						N	N	N*					М	M	Q	Q	Q		
	1.5																			Р	Q	Q				
	2.2				J*										P*					Q	Q	Q				
	3.3																									
	4.7												P*	P*						Q*	Q*	Q*				
L	10											P*	Р							Q*	Q*	Q				
	22																		Q*							
	47																									
	100																									
	WVDC	16	25	50	6.3	10	16	25	50	100	200	6.3	10	16	25	50	100	200	6.3	10	16	25	50	100	200	500
	SIZE		LD02	2				LD03				LD05					LD06									

Letter	А	С	E	G	J	К	М	N	Р	Q	Х	Y	Z				
Max.	0.33	0.56	0.71	0.90	0.94	1.02	1.27	1.40	1.52	1.78	2.29	2.54	2.79				
Thickness	(0.013)	(0.022)	(0.028)	(0.035)	(0.037)	(0.040)	(0.050)	(0.055)	(0.060)	(0.070)	(0.090)	(0.100)	(0.110)				
	PAPER							EMBOSSED									

= Under Development



112916

MLCC Tin/Lead Termination "B"

X7R – Capacitance Range

PREFERRED SIZES ARE SHADED

SIZE					LD10					LD	12		LC	013		LD	20		LC	014			
Solderin	g			Re	eflow On	ly				Reflov	v Only		Reflo	w Only		Reflow	w Only		Reflo	w Only			
Packagir	ng				r/Embos					All Emb				bossed			bossed			bossed			
(L) Length	mm				20 + 0.2	-				4.50 ±				± 0.30			± 0.50		-	± 0.25			
	(in.)				26 ± 0.0					(0.177 ±				± 0.012)			(0.224 ± 0.020)			(0.225 ± 0.010)			
W) Width	mm				50 ± 0.2					3.20 ±				± 0.40			± 0.40		6.35 ± 0.25				
	(in.)									(0.126 ±				± 0.016)			± 0.016)			± 0.010)			
(t) Terminal	mm (in.)				50 ± 0.2					0.61 ±				± 0.36 ± 0.014)			± 0.39		0.64 ± 0.39 (0.025 ± 0.015)				
WVDC	(in.)	10	16	25	20 ± 0.0 50	10)	200	500	50	(0.024 ±	200	500	50	± 0.014) 100	25	<u>(0.025</u> : 50	<u>± 0.015)</u> 100	200	50	100			
Cap	100	10	10	20	50	100	200	500	- 50	100	200	500	50	100	20	50	100	200	50	100			
(pF)	150																						
(рт)	220																						
	330															†		\geq					
	470															×	\langle	<u> </u>)) Ti	-			
	680																			-			
	1000															Ť							
	1500	J	J	J	J	J	J	М										T					
	2200	J	J	J	J	J	J	М											i.				
	3300	J	J	J	J	J	J	М															
	4700	J	J	J	J	J	J	М															
	6800	J	J	J	J	J	J	М															
	0.010	J	J	J	J	J	J	М	K	K	K	К	М	М		Х	X	X	М	Р			
	0.015	J	J	J	J	J	J	Р	K	K	K	P	M	M		X	X	X	M	P			
	0.022	J	J	J	J	J	J	Q	K	K K	K	P	M	M		X X	X X	X	M	P P			
	0.033	J	J	J	J	J	J	Q	K		K	X	M	M			1	X	M	P			
	0.047	J J	J J	J J	J J	J	J M		K K	K K	K K	ZZ	M	M		X X	X X	X X	M	P			
	0.008	J	J	J	J	J	M		K	K	K	Z	M	M		X	X	X	M	P			
	0.15	J	J	J	J	M	Z		ĸ	ĸ	P	-	M	M		x	x	x	M	P			
	0.22	J	J	J	J	P	Z		ĸ	ĸ	P		м	M		x	x	x	M	P			
	0.33	J	J	J	J	Q			K	M	X		M	M		X	X	X	M	P			
	0.47	M	M	M	M	Q			ĸ	P			M	М		X	X	X	M	P			
	0.68	М	М	Р	х	Х			М	Q			М	Р		х	x		М	Р			
	1.0	Ν	Ν	Р	Х	Z			М	X			М	Р		Х	X		М	Р			
	1.5	Ν	Ν	Z	Z	Z			Z	Z			М			X	X		М	X			
	2.2	Х	Х	Z	Z	Z			Z	Z						Х	X		М				
	3.3	Х	Х	Z	Z				Z							Х	Z						
	4.7	X	X	Z	Z				Z	Z						X	Z						
	10	Z	Z	Z	Z										7	Z	Z			├───┤			
	22 47	Z	Z												Z								
	47	Z																					
	WVDC	10	16	25	50	100	200	500	50	100	200	500	50	100	25	50	100	200	50	100			
SIZE	WVDC	10	10	25	LD10	100	200	500	50	LD		500		013	25		20	200)14			
0.22									l														

Letter	А	С	E	G	ſ	К	М	N	Р	Q	Х	Y	Z			
Max.	0.33	0.56	0.71	0.90	0.94	1.02	1.27	1.40	1.52	1.78	2.29	2.54	2.79			
Thickness	(0.013)	(0.022)	(0.028)	(0.035)	(0.037)	(0.040)	(0.050)	(0.055)	(0.060)	(0.070)	(0.090)	(0.100)	(0.110)			
	PAPER							EMBOSSED								



